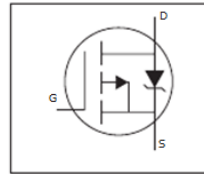


HEXFET[®] 功率MOSFET

特点

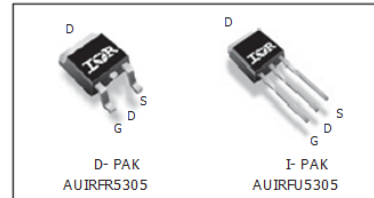
- ▣ 高级平面技术
- ▣ 低导通电阻
- ▣ 动态的dv/dt额定值
- ▣ 175 °C工作温度
- ▣ 快速开关
- ▣ 全额定雪崩
- ▣ 重复性雪崩中允许多达TJMAX
- ▣ 无铅, 符合RoHS
- ▣ 汽车合格*



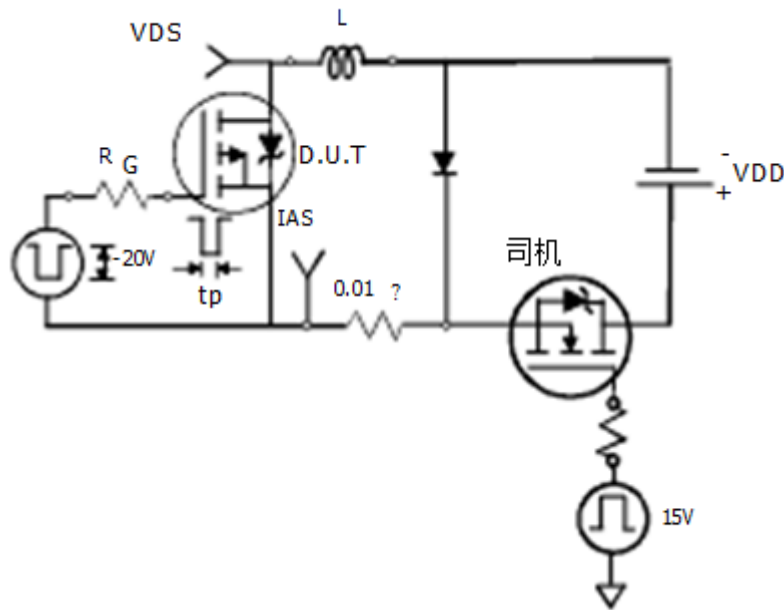
$V_{(BR)DSS}$	-55V
$R_{DS(on)}$ 马克斯	0.065Ω
I_D	-31A

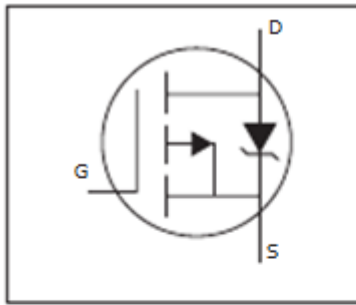
描述

专为汽车应用, 这种细胞
HEXFET功率MOSFET的平面设计采用了
最新的加工技术, 以实现低导通电阻元
硅片面积。这样做的好处结合快速开关
速度和坚固耐用的设备的设计, HEXFET功率
MOSFET是众所周知的, 为设计者提供了一个
非常高效, 在汽车使用可靠的设备
和各种其他应用程序。

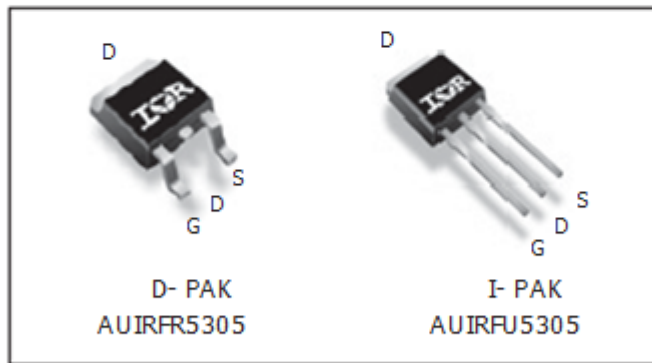


G	D	S
门	漏	来源

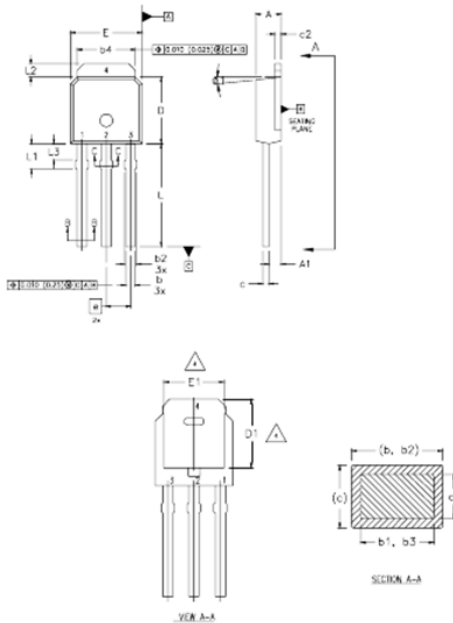




$V_{(BR) DSS}$	-55V
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I_D	-31A



G	D	S
门	漏	来源

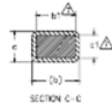
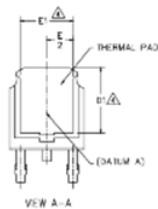
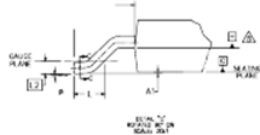
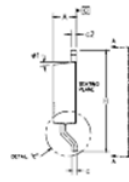
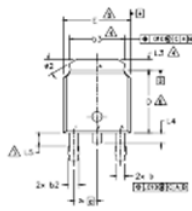


- NOTES:
- 1 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
 - 2 DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 - 3 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 - 4 THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1. LEAD DIMENSION UNCONTROLLED IN L2.
 - 5
 - 6 DIMENSION b1, b3 APPLY TO BASIC METAL ONLY.
 - 7 OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA.
 - 8 CONTROLLING DIMENSION : INCHES.

LEAD ASSIGNMENTS

- KEY:
- 1- GATE
 - 2- DRAIN
 - 3- SOURCE
 - 4- DRN

SYMBOL	DIMENSIONS		DIMENSIONS		NOTES
	MIL.	MAX.	MIL.	MAX.	
A	2.18	2.50	0.88	0.94	
A1	0.89	1.14	0.25	0.45	
b	0.54	0.85	0.20	0.40	
b1	0.54	0.75	0.20	0.31	4
b2	0.79	1.14	0.30	0.45	
b3	0.79	1.04	0.30	0.41	
b4	5.00	3.48	0.195	0.215	4
c	0.48	0.67	0.19	0.24	
c1	2.41	2.56	0.115	0.025	
c2	3.46	3.68	0.18	0.05	
D	5.87	6.22	0.225	0.245	Δ, 4
D1	5.21	-	0.205	-	4
E	6.30	6.73	0.250	0.265	Δ, 4
E1	4.32	-	0.170	-	4
h	2.29		0.090 (3C)		
L	0.89	0.80	0.250	0.300	
L1	1.91	2.26	0.575	0.600	
L2	0.89	1.21	0.225	0.060	4
L3	1.14	1.52	0.440	0.060	5
W	0"	10"	0"	10"	



- NOTES:
 1- DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994
 2- DIMENSION ARE SHOWN IN INCHES (MILLIMETERS)
 Δ LEAD DIMENSION UNCONTROLLED IN I.S.
 Δ DIMENSION D1, E1, L3 & L3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
 Δ SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [.015 AND 0.25] FROM THE LEAD TIP.
 Δ DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.15] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE CLOSEST EXTREMES OF THE PLASTIC BODY.
 Δ DIMENSION b1 & L1 APPLIED TO BASE METAL ONLY.
 Δ DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
 Δ OUTLINE CONFORMS TO JEDEC OUTLINE 10-252AA.

SYMBOL	DIMENSIONS				UNIT
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.35	.086	.094	4
A1	-	0.15	-	.006	
b	0.64	0.89	.025	.035	7
b1	0.65	0.79	.025	.031	
b2	0.75	1.14	.030	.045	4
b3	4.95	5.46	.195	.215	
c	0.46	0.61	.018	.024	7
c1	0.41	0.56	.016	.022	
c2	0.46	0.69	.018	.035	6
D	5.97	6.22	.235	.245	
D1	5.21	-	.206	-	4
E	6.25	6.75	.250	.265	
E1	4.32	-	.170	-	4
e	2.28	BSC	.090	BSC	
H	9.40	10.41	.370	.410	4
L	1.40	1.78	.055	.070	
L1	2.74	BSC	.108	REF.	4
L2	0.51	BSC	.020	BSC	
L3	0.88	1.27	.035	.050	4
L4	-	1.02	-	.040	
L5	1.14	1.52	.045	.060	5
e	0"	10"	0"	10"	
#1	0"	15"	0"	15"	5
#2	25"	35"	25"	35"	

LEAD ASSIGNMENTS

JEDEC

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

IGBT & CoPAK

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR